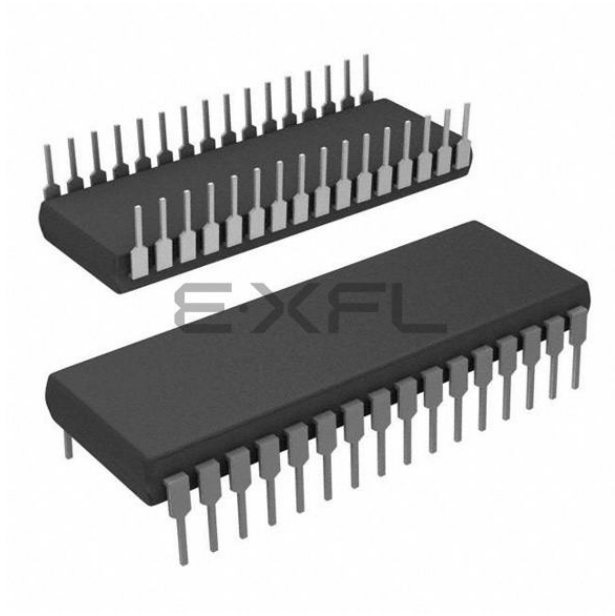
Infineon Technologies - MB95F334KP-G-SH-SNE2 Datasheet



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	F²MC-8FX
Core Size	8-Bit
Speed	16MHz
Connectivity	I²C, LINbus, SIO, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	29
Program Memory Size	20KB (20K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1008 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 5.5V
Data Converters	A/D 8x8/10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	32-SDIP (0.400", 10.16mm)
Supplier Device Package	32-SDIP
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb95f334kp-g-sh-sne2

Contents

1. Product Line-up

Part number / Parameter	MB95F332H	MB95F333H	MB95F334H	MB95F332K	MB95F333K	MB95F334K
Type	Flash memory product					
Clock supervisor counter	It supervises the main clock oscillation.					
Program ROM capacity	8 Kbyte	12 Kbyte	20 Kbyte	8 Kbyte	12 Kbyte	20 Kbyte
RAM capacity	240 bytes	496 bytes	1008 bytes	240 bytes	496 bytes	1008 bytes
Low-voltage detection reset	No			Yes		
Reset input	Dedicated			Selected by software		
CPU functions	Number of basic instructions : 136 Instruction bit length : 8 bits Instruction length : 1 to 3 bytes Data bit length : 1, 8 and 16 bits Minimum instruction execution time : 61.5 ns (with machine clock = 16.25 MHz) Interrupt processing time : 0.6 µs (with machine clock = 16.25 MHz)					
General-purpose I/O	I/O ports (Max): 28 CMOS I/O: 25 N-ch open drain: 3			I/O ports (Max): 29 CMOS I/O: 25 N-ch open drain: 4		
Time-base timer	Interrupt cycle: 0.256 ms to 8.3 s (when external clock = 4 MHz)					
Hardware/software watchdog timer	Reset generation cycle Main oscillation clock at 10 MHz: 105 ms (Min) The sub-CR clock can be used as the source clock of the hardware watchdog timer.					
Wild register	It can be used to replace three bytes of data.					
LIN-UART	A wide range of communication speeds can be selected by a dedicated reload timer. Clock-synchronous serial data transfer and clock-asynchronous serial data transfer is enabled. The LIN function can be used as a LIN master or a LIN slave.					
8/10-bit A/D converter	8 channels					
	8-bit resolution and 10-bit resolution can be chosen.					
8/16-bit composite timer	2 channels					
	The timer can be configured as an "8-bit timer x 2 channels" or a "16-bit timer x 1 channel". It has built-in timer function, PWC function, PWM function and input capture function. Count clock: it can be selected from internal clocks (seven types) and external clocks. It can output square wave.					
External interrupt	10 channels					
	Interrupt by edge detection (The rising edge, falling edge, or both edges can be selected.) It can be used to wake up the device from different standby modes.					
On-chip debug	1-wire serial control It supports serial writing. (asynchronous mode)					

(Continued)

2. Packages and Corresponding Products

Part number / Package	MB95F332H	MB95F332K	MB95F333H	MB95F333K	MB95F334H	MB95F334K
FPT-32P-M30	O	O	O	O	O	O
DIP-32P-M06	O	O	O	O	O	O
LCC-32P-M19	O	O	O	O	O	O

O: Available

3. Differences Among Products and Notes On Product Selection

■ • Current consumption
When using the on-chip debug function, take account of the current consumption of flash erase/write.
For details of current consumption, see “Electrical Characteristics.

■ • Package
For details of information on each package, see “Packages and Corresponding Products” and “Package Dimension”.

■ • Operating voltage
The operating voltage varies, depending on whether the on-chip debug function is used or not.
For details of the operating voltage, see “Electrical Characteristics”.

■ • On-chip debug function
The on-chip debug function requires that V_{CC}, V_{SS} and one serial wire be connected to an evaluation tool.

5. Pin Description

Pin no.		Pin name	I/O circuit type*4	Function
LQFP32*1 & QFN32*2	SH-DIP32*3			
1	5	PG2	C	General-purpose I/O port
		X1A		Subclock I/O oscillation pin
		SNI2		Trigger input pin for the position detection function of the MPG waveform sequencer
2	6	PG1	C	General-purpose I/O port
		X0A		Subclock input oscillation pin
		SNI1		Trigger input pin for the position detection function of the MPG waveform sequencer
3	7	V_{CC}	—	Power supply pin
4	8	C	—	Capacitor connection pin
5	9	P67	D	General-purpose I/O port High-current pin
		PPG21		8/16-bit PPG ch. 2 output pin
		TRG1		16-bit PPG ch. 1 trigger input pin
		OPT5		MPG waveform sequencer output pin
6	10	P66	D	General-purpose I/O port High-current pin
		PPG20		8/16-bit PPG ch. 2 output pin
		PPG1		16-bit PPG ch. 1 output pin
		OPT4		MPG waveform sequencer output pin
7	11	P65	D	General-purpose I/O port High-current pin
		PPG11		8/16-bit PPG ch. 1 output pin
		OPT3		MPG waveform sequencer output pin
8	12	P64	D	General-purpose I/O port High-current pin
		EC1		8/16-bit composite timer ch. 1 clock input pin
		PPG10		8/16-bit PPG ch. 1 output pin
		OPT2		MPG waveform sequencer output pin
9	13	P63	D	General-purpose I/O port High-current pin
		TO11		8/16-bit composite timer ch. 1 output pin
		PPG01		8/16-bit PPG ch. 0 output pin
		OPT1		MPG waveform sequencer output pin

(Continued)

■ Power supply pins

To reduce unnecessary electro-magnetic emission, prevent malfunctions of strobe signals due to an increase in the ground level, and conform to the total output current standard, always connect the V_{CC} pin and the V_{SS} pin to the power supply and ground outside the device. In addition, connect the current supply source to the V_{CC} pin and the V_{SS} pin with low impedance.

It is also advisable to connect a ceramic capacitor of approximately 0.1 µF as a bypass capacitor between the V_{CC} pin and the V_{SS} pin at a location close to this device.

■ DBG pin

Connect the DBG pin directly to an external pull-up resistor.

To prevent the device from unintentionally entering the debug mode due to noise, minimize the distance between the DBG pin and the V_{CC} or V_{SS} pin when designing the layout of the printed circuit board.

The DBG pin should not stay at “L” level after power-on until the reset output is released.

■ $\overline{\text{RST}}$ pin

Connect the $\overline{\text{RST}}$ pin directly to an external pull-up resistor.

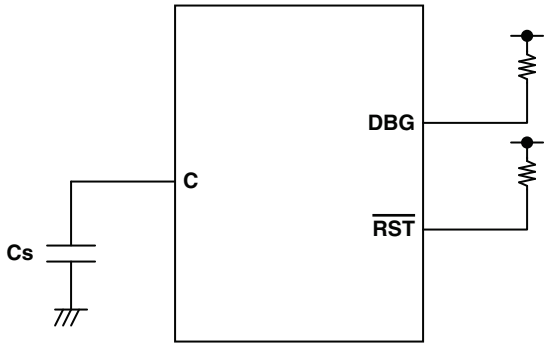
To prevent the device from unintentionally entering the reset mode due to noise, minimize the distance between the $\overline{\text{RST}}$ pin and the V_{CC} or V_{SS} pin when designing the layout of the printed circuit board.

The $\overline{\text{RST}}$/PF2 pin functions as the reset input/output pin after power-on. In addition, the reset output of the $\overline{\text{RST}}$/PF2 pin can be enabled by the RSTOE bit of the SYSC register, and the reset input function and the general purpose I/O function can be selected by the RSTEN bit of the SYSC register.

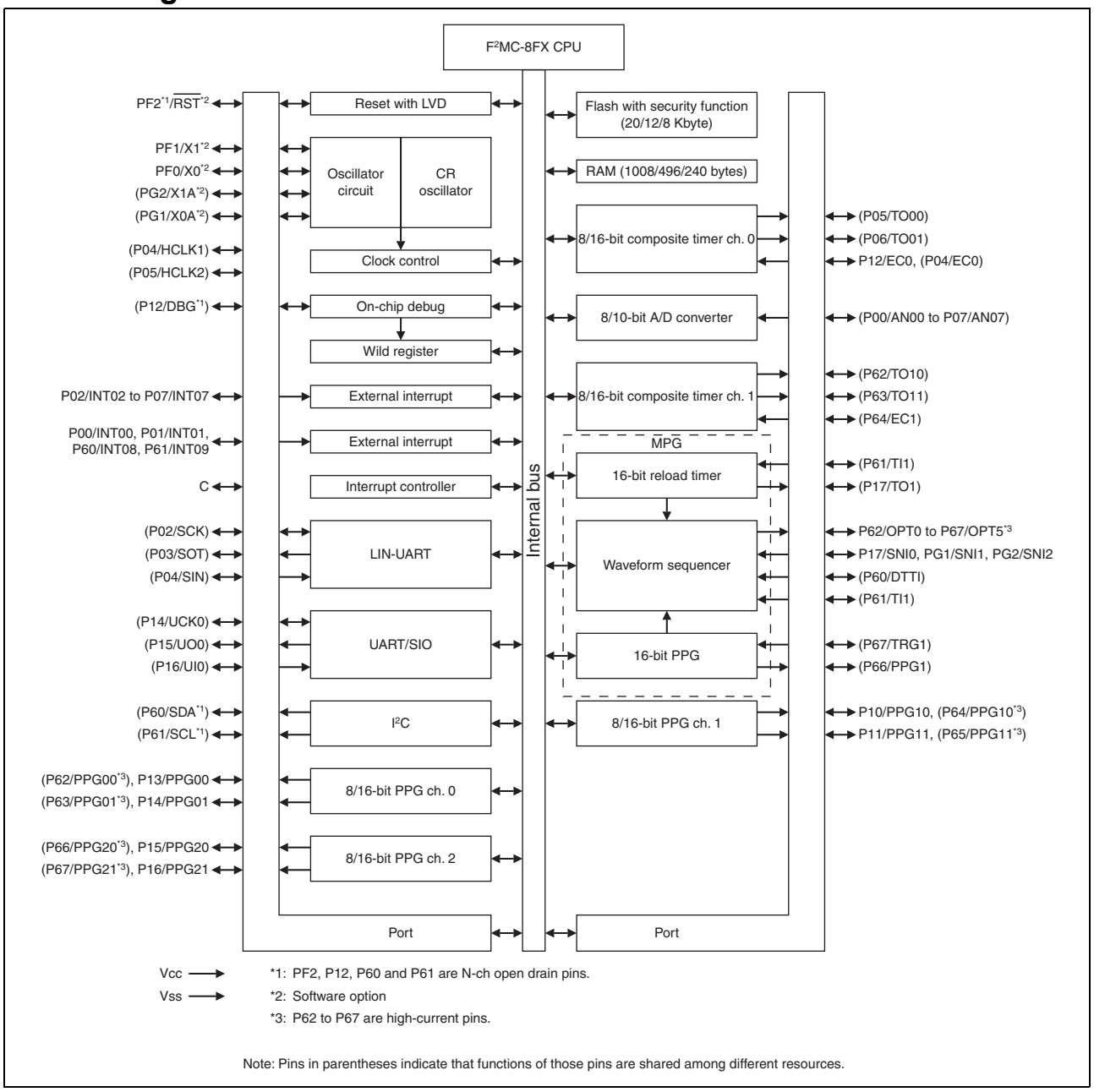
■ C pin

Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The bypass capacitor for the V_{CC} pin must have a capacitance larger than C_S. For the connection to a smoothing capacitor C_S, see the diagram below. To prevent the device from unintentionally entering a mode to which the device is not set to transit due to noise, minimize the distance between the C pin and C_S and the distance between C_S and the V_{SS} pin when designing the layout of a printed circuit board.

• DBG/$\overline{\text{RST}}$/C pins connection diagram



9. Block Diagram

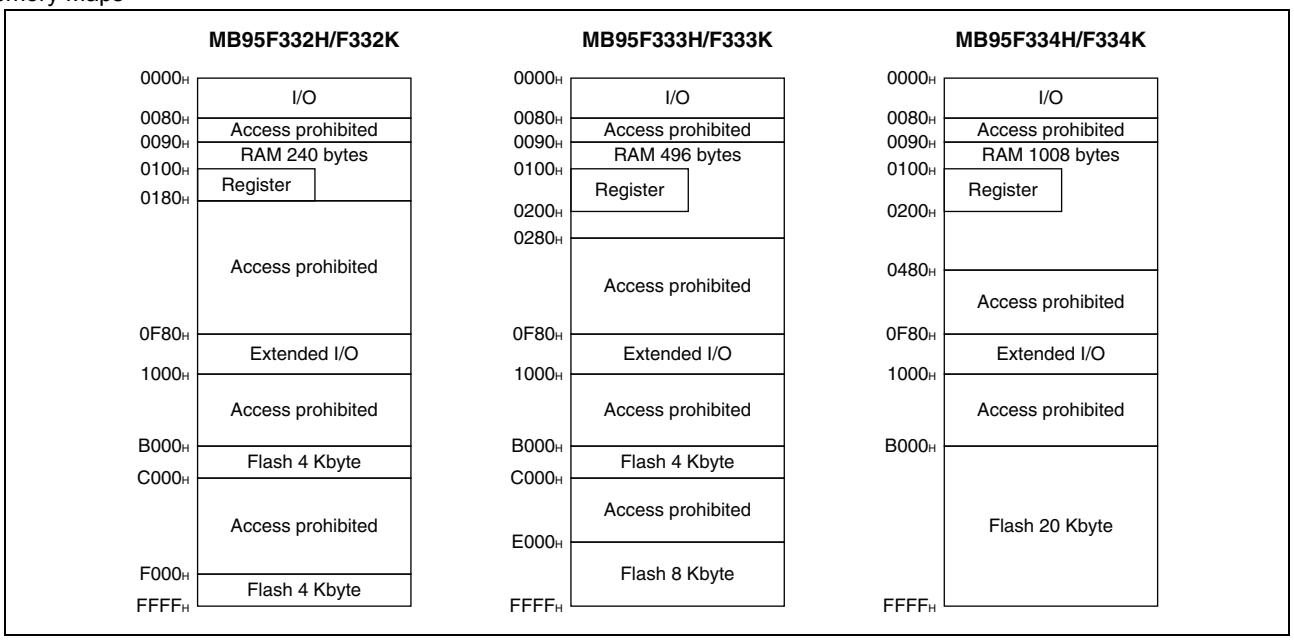


10. CPU Core

■ Memory Space

The memory space of the MB95330H Series is 64 Kbyte in size, and consists of an I/O area, a data area, and a program area. The memory space includes areas intended for specific purposes such as general-purpose registers and a vector table. The memory maps of the MB95330H Series are shown below.

■ Memory Maps


MB95F332H/F332K
0000H
I/O
0080H
Access prohibited
0090H
RAM 240 bytes
0100H
Register
0180H
Access prohibited
0F80H
Extended I/O
1000H
Access prohibited
B000H
Flash 4 Kbyte
C000H
Access prohibited
F000H
Flash 4 Kbyte
FFFFH
MB95F333H/F333K
0000H
I/O
0080H
Access prohibited
0090H
RAM 496 bytes
0100H
Register
0200H
0280H
Access prohibited
0F80H
Extended I/O
1000H
Access prohibited
B000H
Flash 4 Kbyte
C000H
Access prohibited
E000H
Flash 8 Kbyte
FFFFH
MB95F334H/F334K
0000H
I/O
0080H
Access prohibited
0090H
RAM 1008 bytes
0100H
Register
0200H
0480H
Access prohibited
0F80H
Extended I/O
1000H
Access prohibited
B000H
Flash 20 Kbyte
FFFFH

Address	Register abbreviation	Register name	R/W	Initial value
$0F92_H$	T01CR0	8/16-bit composite timer 01 status control register 0 ch. 0	R/W	00000000_B
$0F93_H$	T00CR0	8/16-bit composite timer 00 status control register 0 ch. 0	R/W	00000000_B
$0F94_H$	T01DR	8/16-bit composite timer 01 data register ch. 0	R/W	00000000_B
$0F95_H$	T00DR	8/16-bit composite timer 00 data register ch. 0	R/W	00000000_B
$0F96_H$	TMCR0	8/16-bit composite timer 00/01 timer mode control register ch. 0	R/W	00000000_B
$0F97_H$	T11CR0	8/16-bit composite timer 11 status control register 0 ch. 1	R/W	00000000_B
$0F98_H$	T10CR0	8/16-bit composite timer 10 status control register 0 ch. 1	R/W	00000000_B
$0F99_H$	T11DR	8/16-bit composite timer 11 data register ch. 1	R/W	00000000_B
$0F9A_H$	T10DR	8/16-bit composite timer 10 data register ch. 1	R/W	00000000_B
$0F9B_H$	TMCR1	8/16-bit composite timer 10/11 timer mode control register ch. 1	R/W	00000000_B
$0F9C_H$	PPS01	8/16-bit PPG01 cycle setting buffer register ch. 0	R/W	11111111_B
$0F9D_H$	PPS00	8/16-bit PPG00 cycle setting buffer register ch. 0	R/W	11111111_B
$0F9E_H$	PDS01	8/16-bit PPG01 duty setting buffer register ch. 0	R/W	11111111_B
$0F9F_H$	PDS00	8/16-bit PPG00 duty setting buffer register ch. 0	R/W	11111111_B
$0FA0_H$	PPS11	8/16-bit PPG11 cycle setting buffer register ch. 1	R/W	11111111_B
$0FA1_H$	PPS10	8/16-bit PPG10 cycle setting buffer register ch. 1	R/W	11111111_B
$0FA2_H$	PDS11	8/16-bit PPG11 duty setting buffer register ch. 1	R/W	11111111_B
$0FA3_H$	PDS10	8/16-bit PPG10 duty setting buffer register ch. 1	R/W	11111111_B
$0FA4_H$	PPGS	8/16-bit PPG startup register	R/W	00000000_B
$0FA5_H$	REVC	8/16-bit PPG output reverse register	R/W	00000000_B
$0FA6_H$	PPS21	8/16-bit PPG21 cycle setting buffer register ch. 2	R/W	11111111_B
$0FA7_H$	PPS20	8/16-bit PPG20 cycle setting buffer register ch. 2	R/W	11111111_B
$0FA8_H$	TMRH1	16-bit timer register (upper) ch. 1	R/W	00000000_B
	TMRLRH1	16-bit reload register (upper) ch. 1		
$0FA9_H$	TMRL1	16-bit timer register (lower) ch. 1	R/W	00000000_B
	TMRLRL1	16-bit reload register (lower) ch. 1		
$0FAA_H$	PDS21	8/16-bit PPG21 duty setting buffer register ch. 2	R/W	11111111_B
$0FAB_H$	PDS20	8/16-bit PPG20 duty setting buffer register ch. 2	R/W	11111111_B
$0FAC_H$ to $0FAF_H$	—	(Disabled)	—	—
$0FB0_H$	PDCRH1	16-bit PPG down counter register (upper) ch. 1	R	00000000_B
$0FB1_H$	PDCRL1	16-bit PPG down counter register (lower) ch. 1	R	00000000_B
$0FB2_H$	PCSRH1	16-bit PPG cycle setting buffer register (upper) ch. 1	R/W	11111111_B
$0FB3_H$	PCSRL1	16-bit PPG cycle setting buffer register (lower) ch. 1	R/W	11111111_B
$0FB4_H$	PDUTH1	16-bit PPG duty setting buffer register (upper) ch. 1	R/W	11111111_B
$0FB5_H$	PDUTL1	16-bit PPG duty setting buffer register (lower) ch. 1	R/W	11111111_B

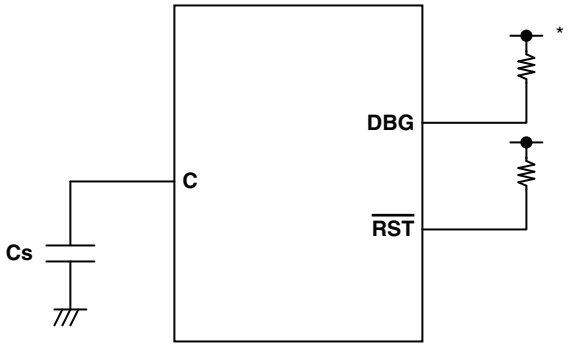
(Continued)

*1: The value varies depending on the operating frequency, the machine clock and the analog guaranteed range.

*2: This value becomes 2.88 V when the low-voltage detection reset is used.

*3: Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The bypass capacitor for the V_{CC} pin must have a capacitance larger than C_S. For the connection to a smoothing capacitor C_S, see the diagram below. To prevent the device from unintentionally entering an unknown mode due to noise, minimize the distance between the C pin and C_S and the distance between C_S and the V_{SS} pin when designing the layout of a printed circuit board.

- DBG / $\overline{\text{RST}}$ / C pins connection diagram



*: Since the DBG pin becomes a communication pin in on-chip debug mode, set a pull-up resistor value suiting the input/output specifications of P12/DBG/EC0.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

13.4.2 Source Clock/Machine Clock

(V_{CC} = 5.0 V±10%, V_{SS} = 0.0 V, T_A = –40°C to +85°C)

Parameter	Symbol	Pin name	Value			Unit	Remarks
			Min	Typ	Max		
Source clock cycle time*1	t_{SCLK}	—	61.5	—	2000	ns	When the main external clock is used Min: F_{CH} = 32.5 MHz, divided by 2 Max: F_{CH} = 1 MHz, divided by 2
			80	—	1000	ns	When the main CR clock is used Min: F_{CRH} = 12.5 MHz Max: F_{CRH} = 1 MHz
			—	61	—	µs	When the sub-oscillation clock is used F_{CL} = 32.768 kHz, divided by 2
			—	20	—	µs	When the sub-CR clock is used F_{CRL} = 100 kHz, divided by 2
Source clock frequency	F_{SP}	—	0.5	—	16.25	MHz	When the main oscillation clock is used
			1	—	12.5	MHz	When the main CR clock is used
	F_{SPL}		—	16.384	—	kHz	When the sub-oscillation clock is used
			—	50	—	kHz	When the sub-CR clock is used F_{CRL} = 100 kHz, divided by 2
Machine clock cycle time*2 (minimum instruction execution time)	t_{MCLK}	—	61.5	—	32000	ns	When the main oscillation clock is used Min: F_{SP} = 16.25 MHz, no division Max: F_{SP} = 0.5 MHz, divided by 16
			80	—	16000	ns	When the main CR clock is used Min: F_{SP} = 12.5 MHz Max: F_{SP} = 1 MHz, divided by 16
			61	—	976.5	µs	When the sub-oscillation clock is used Min: F_{SPL} = 16.384 kHz, no division Max: F_{SPL} = 16.384 kHz, divided by 16
			20	—	320	µs	When the sub-CR clock is used Min: F_{SPL} = 50 kHz, no division Max: F_{SPL} = 50 kHz, divided by 16
Machine clock frequency	F_{MP}	—	0.031	—	16.25	MHz	When the main oscillation clock is used
			0.0625	—	12.5	MHz	When the main CR clock is used
	F_{MPL}		1.024	—	16.384	kHz	When the sub-oscillation clock is used
			3.125	—	50	kHz	When the sub-CR clock is used F_{CRL} = 100 kHz

*1: This is the clock before it is divided according to the division ratio set by the machine clock divide ratio select bits (SYCC:DIV1 and DIV0). This source clock is divided to become a machine clock according to the divide ratio set by the machine clock divide ratio select bits (SYCC:DIV1 and DIV0). In addition, a source clock can be selected from the following.

- Main clock divided by 2
- Main CR clock
- Subclock divided by 2
- Sub-CR clock divided by 2

*2: This is the operating clock of the microcontroller. A machine clock can be selected from the following.

- Source clock (no division)
- Source clock divided by 4
- Source clock divided by 8
- Source clock divided by 16

13.4.3 External Reset

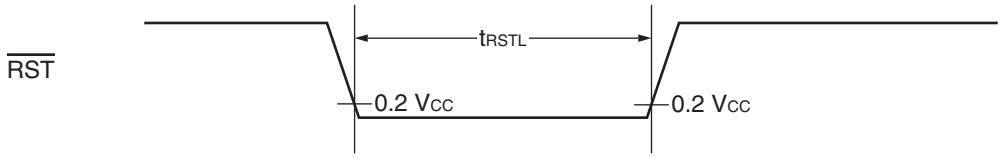
(V_{CC} = 5.0 V±10%, V_{SS} = 0.0 V, T_A = –40°C to +85°C)

Parameter	Symbol	Value		Unit	Remarks
		Min	Max		
$\overline{RST}$ "L" level pulse width	t_{RSTL}	2 t_{MCLK}*1	—	ns	In normal operation
		Oscillation time of the oscillator*2 + 100	—	µs	In stop mode, subclock mode, subsleep mode, watch mode, and power-on
		100	—	µs	In time-base timer mode

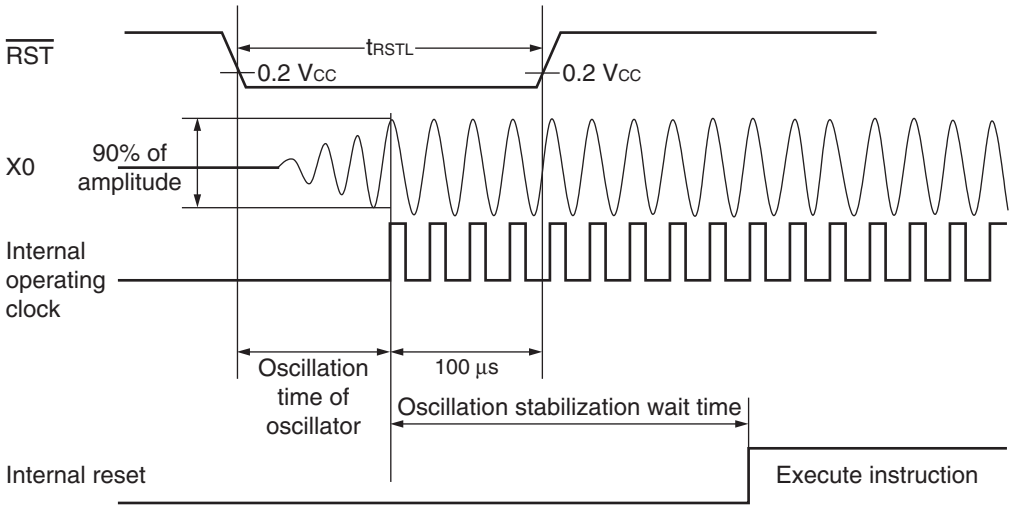
*1: See "(2) Source Clock/Machine Clock" for t_{MCLK}.

*2: The oscillation time of an oscillator is the time for it to reach 90% of its amplitude. The crystal oscillator has an oscillation time of between several ms and tens of ms. The ceramic oscillator has an oscillation time of between hundreds of µs and several ms. The external clock has an oscillation time of 0 ms. The CR oscillator clock has an oscillation time of between several µs and several ms.

- In normal operation



- In stop mode, subclock mode, subsleep mode, watch mode and power-on

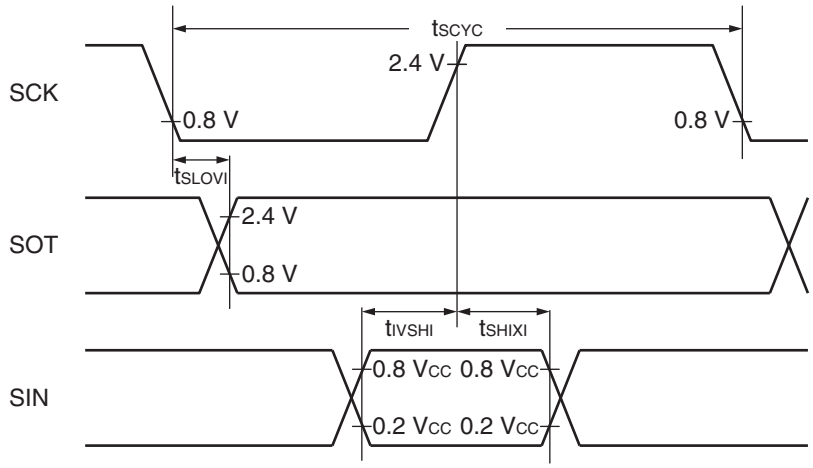


13.4.4 Power-on Reset

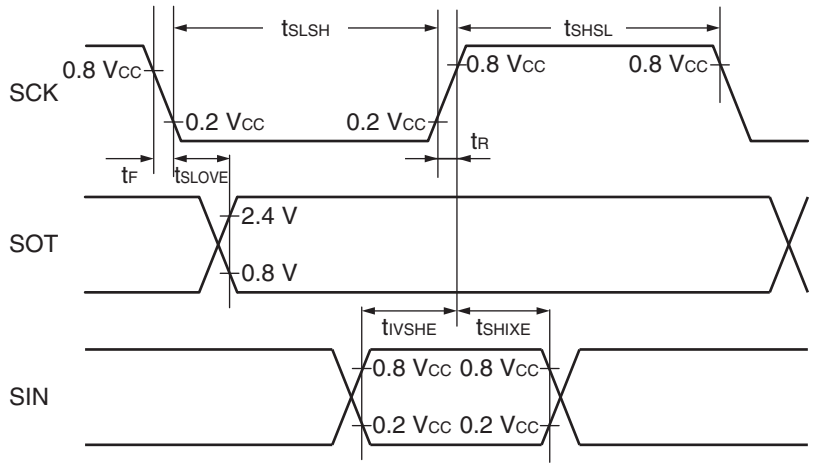
(V_{SS} = 0.0 V, T_A = –40°C to +85°C)

Parameter	Symbol	Condition	Value		Unit	Remarks
			Min	Max		
Power supply rising time	t_R	—	—	50	ms	
Power supply cutoff time	t_{OFF}	—	1	—	ms	Wait time until power-on

- Internal shift clock mode



- External shift clock mode



13.4.8 I²C Timing

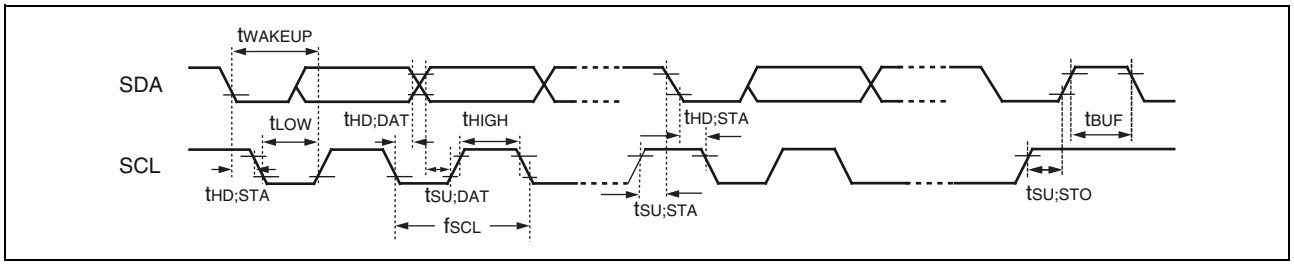
(V_{CC} = 5.0 V±10%, AV_{SS} = V_{SS} = 0.0 V, T_A = −40°C to +85°C)

Parameter	Symbol	Pin name	Condition	Value				Unit
				Stan-dard-mode		Fast-mode		
				Min	Max	Min	Max	
SCL clock frequency	f_{SCL}	SCL	R = 1.7 kΩ, C = 50 pF*1	0	100	0	400	kHz
(Repeated) START condition hold time SDA ↓ → SCL ↓	$t_{HD;STA}$	SCL, SDA		4.0	—	0.6	—	µs
SCL clock "L" width	t_{LOW}	SCL		4.7	—	1.3	—	µs
SCL clock "H" width	t_{HIGH}	SCL		4.0	—	0.6	—	µs
(Repeated) START condition hold time SCL ↑ → SDA ↓	$t_{SU;STA}$	SCL, SDA		4.7	—	0.6	—	µs
Data hold time SCL ↓ → SDA ↓↑	$t_{HD;DAT}$	SCL, SDA		0	3.45*2	0	0.9*3	µs
Data setup time SDA ↓↑ → SCL ↑	$t_{SU;DAT}$	SCL, SDA		0.25	—	0.1	—	µs
STOP condition setup time SCL ↑ → SDA ↑	$t_{SU;STO}$	SCL, SDA		4	—	0.6	—	µs
Bus free time between STOP condition and START condition	t_{BUF}	SCL, SDA		4.7	—	1.3	—	µs

*1: R represents the pull-up resistor of the SCL and SDA lines, and C the load capacitor of the SCL and SDA lines.

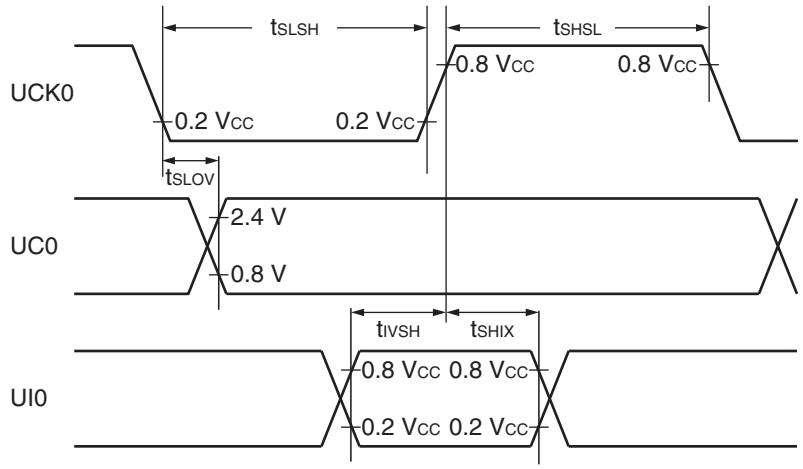
*2: The maximum $t_{HD;DAT}$ in the Standard-mode is applicable only when the time during which the device is holding the SCL signal at "L" (t_{LOW}) does not extend.

*3: A Fast-mode I²C-bus device can be used in a Standard-mode I²C-bus system, provided that the condition of $t_{SU;DAT} \geq 250$ ns is fulfilled.



(Continued)

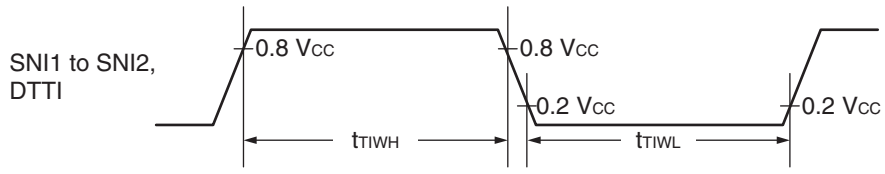
- External shift clock mode



13.4.10 MPG Input Timing

(V_{CC} = 5.0 V±10%, AV_{SS} = V_{SS} = 0.0 V, T_A = −40°C to +85°C)

Parameter	Symbol	Pin name	Condition	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{TIWH} t_{TIWL}	SNI0 to SNI2, DTTI	—	4 t_{MCLK}	—	ns	



13.5 A/D Converter

13.5.1 A/D Converter Electrical Characteristics

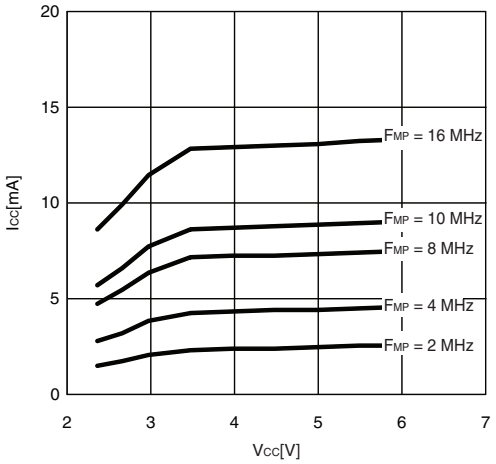
(V_{CC} = 4.0 V to 5.5 V, V_{SS} = 0.0 V, T_A = −40°C to +85°C)

Parameter	Symbol	Value			Unit	Remarks
		Min	Typ	Max		
Resolution	—	—	—	10	bit	
Total error		−3	—	+3	LSB	
Linearity error		−2.5	—	+2.5	LSB	
Differential linear error		−1.9	—	+1.9	LSB	
Zero transition voltage	V_{OT}	V_{SS} − 1.5 LSB	V_{SS} + 0.5 LSB	V_{SS} + 2.5 LSB	V	

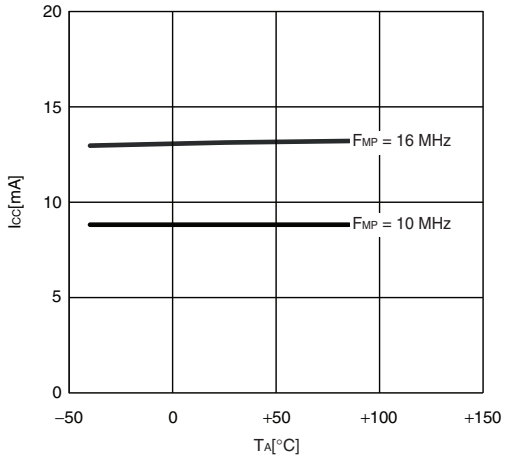
14. Sample Characteristics

■ Power supply current temperature characteristics

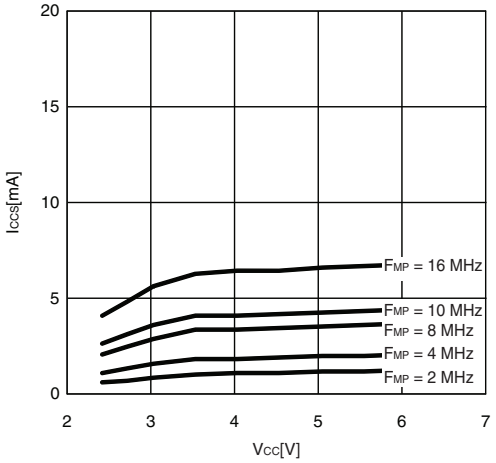
$I_{CC} - V_{CC}$
T_A = +25°C, F_{MP} = 2, 4, 8, 10, 16 MHz (divided by 2)
Main clock mode with the external clock operating



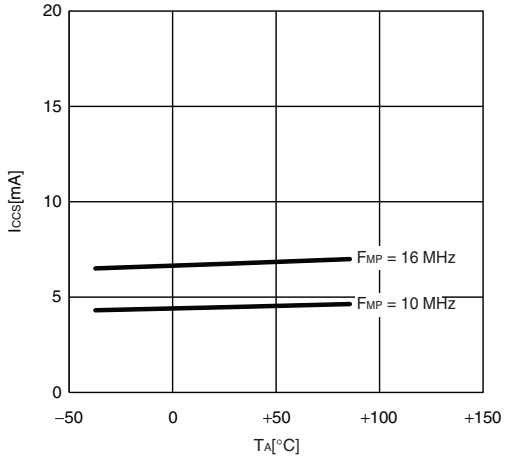
$I_{CC} - T_A$
V_{CC} = 5.5 V, F_{MP} = 10, 16 MHz (divided by 2)
Main clock mode with the external clock operating



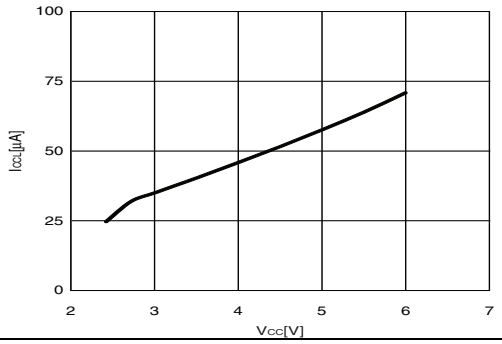
$I_{CCS} - V_{CC}$
T_A = +25°C, F_{MP} = 2, 4, 8, 10, 16 MHz (divided by 2)
Main sleep mode with the external clock operating



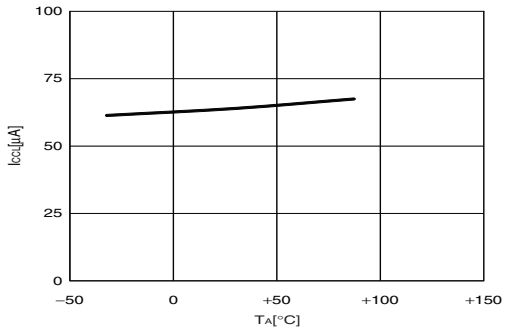
$I_{CCS} - T_A$
V_{CC} = 5.5 V, F_{MP} = 10, 16 MHz (divided by 2)
Main sleep mode with the external clock operating



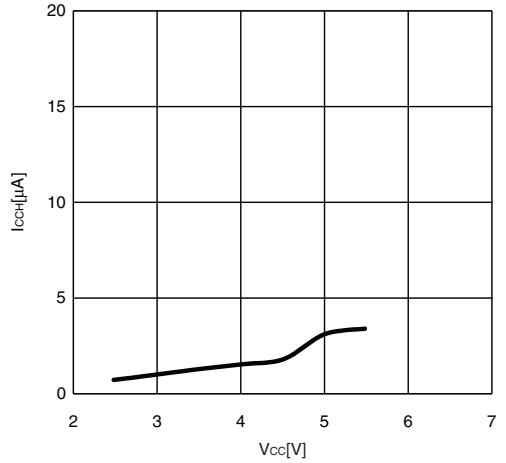
$I_{CCL} - V_{CC}$
T_A = +25°C, F_{MPL} = 16 kHz (divided by 2)
Subclock mode with the external clock operating



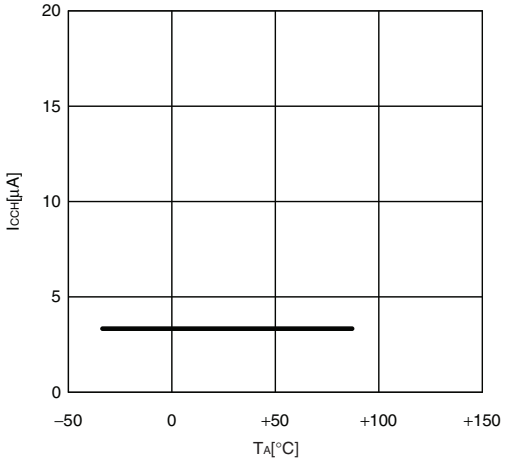
$I_{CCL} - T_A$
V_{CC} = 5.5 V, F_{MPL} = 16 kHz (divided by 2)
Subclock mode with the external clock operating



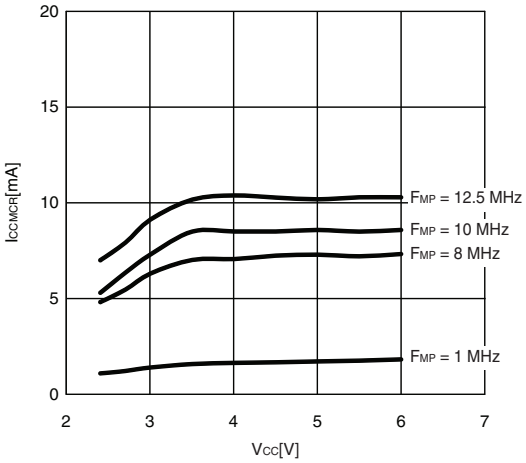
I_{CCH} – V_{CC}
T_A = +25°C, F_{MPL} = (stop)
Substop mode with the external clock stopping



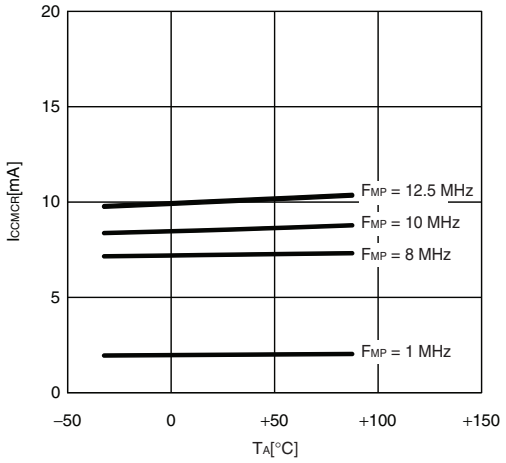
I_{CCH} – T_A
V_{CC} = 5.5 V, F_{MPL} = (stop)
Substop mode with the external clock stopping



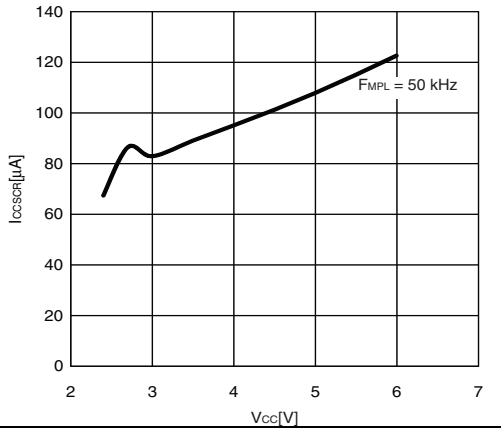
I_{CCMCR} – V_{CC}
T_A = +25°C, F_{MP} = 1, 8, 10, 12.5 MHz (no division)
Main clock mode with the main CR clock operating



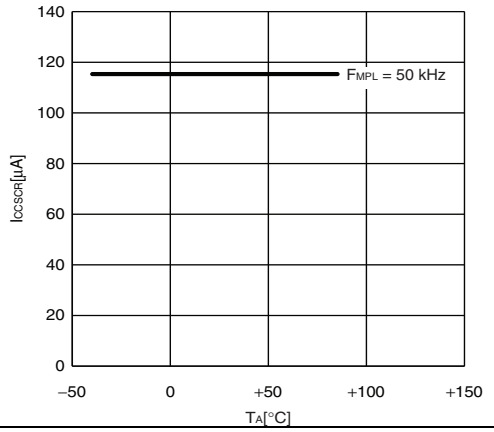
I_{CCMCR} – T_A
V_{CC} = 5.5 V F_{MP} = 1, 8, 10, 12.5 MHz (no division)
Main clock mode with the main CR clock operating



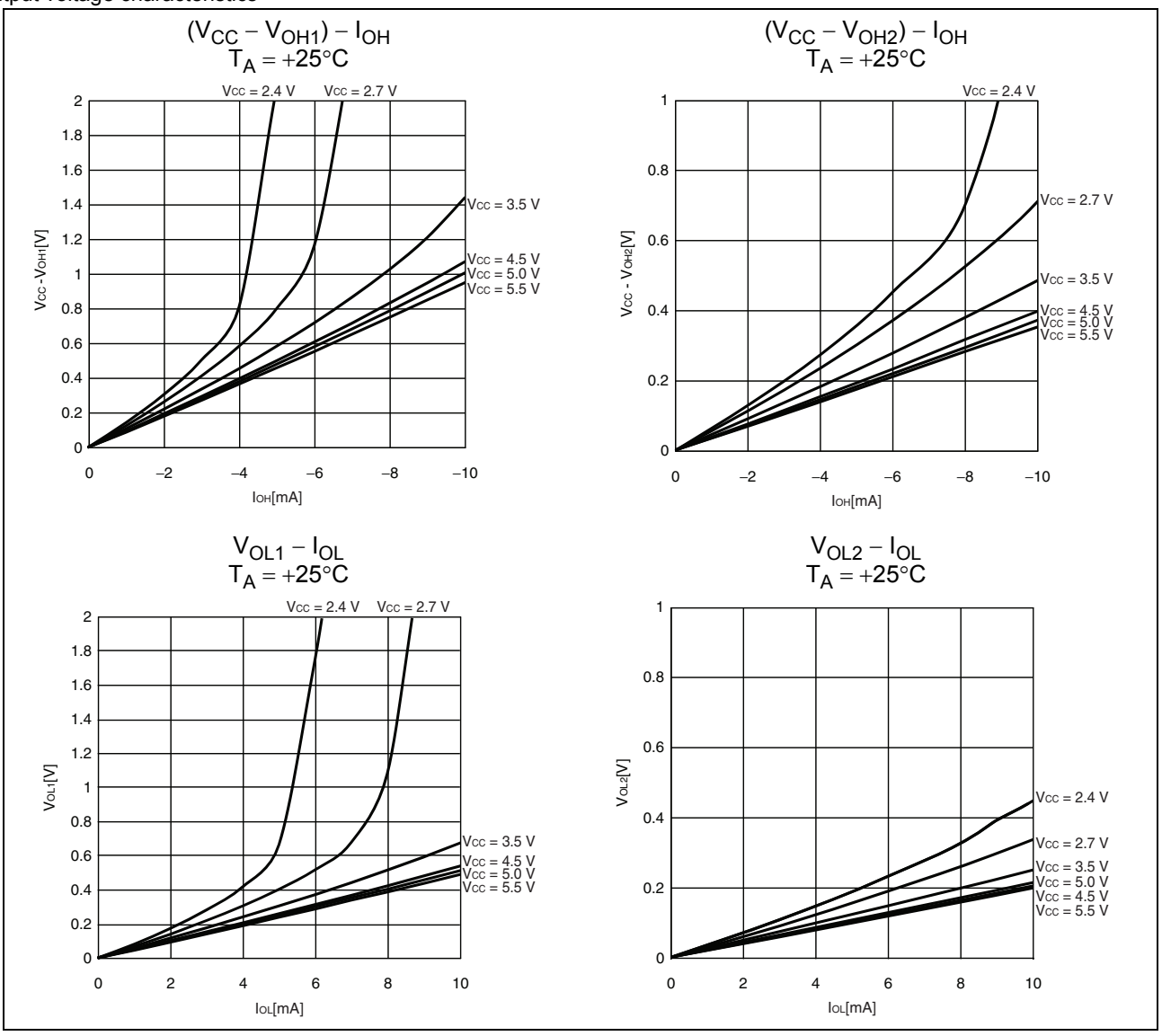
I_{CCSCR} – V_{CC}
T_A = +25°C, F_{MPL} = 50 kHz (divided by 2)
Subclock mode with the sub-CR clock operating

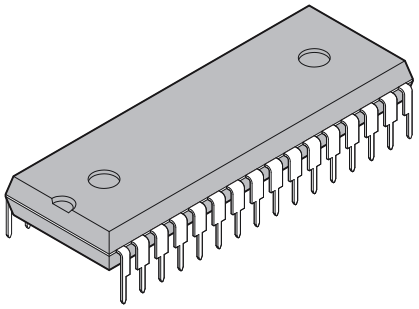


I_{CCSCR} – T_A
V_{CC} = 5.5 V F_{MPL} = 50 kHz (divided by 2)
Subclock mode with the sub-CR clock operating



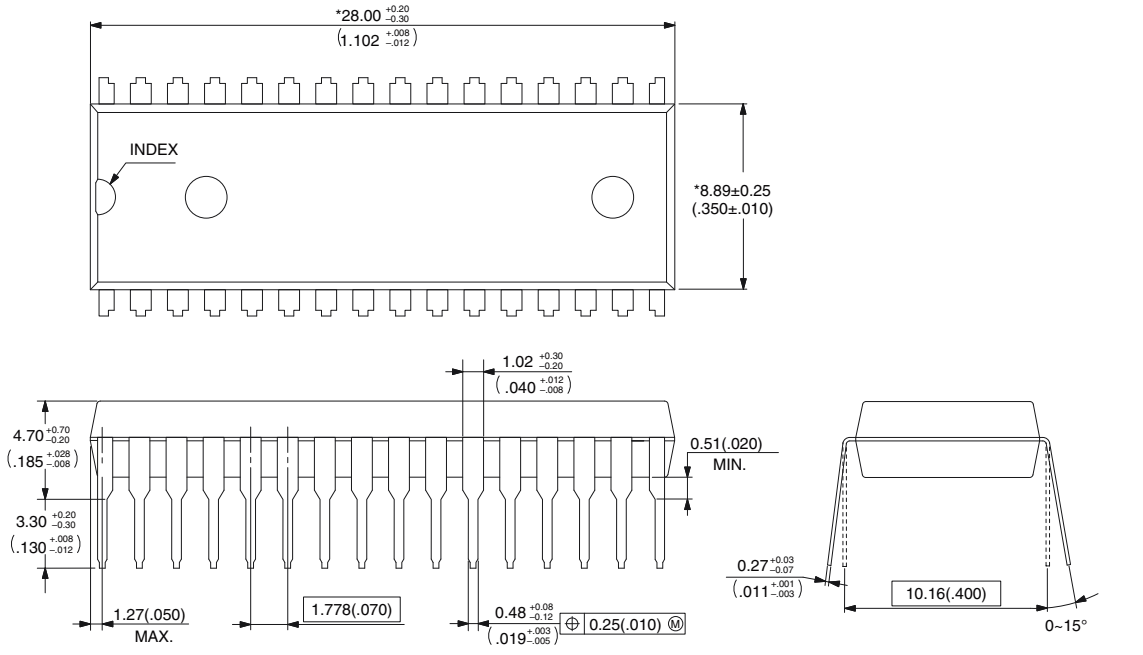
■ Output voltage characteristics



32-pin plastic SH-DIP		
	Lead pitch	1.778 mm
	Low space	10.16 mm
	Sealing method	Plastic mold
(DIP-32P-M06)		

32-pin plastic SH-DIP
(DIP-32P-M06)

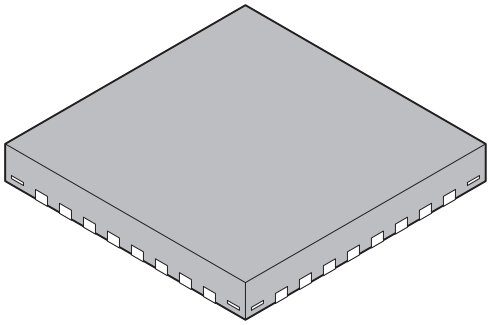
Note 1) * : These dimensions do not include resin protrusion.
Note 2) Pins width and pins thickness include plating thickness.



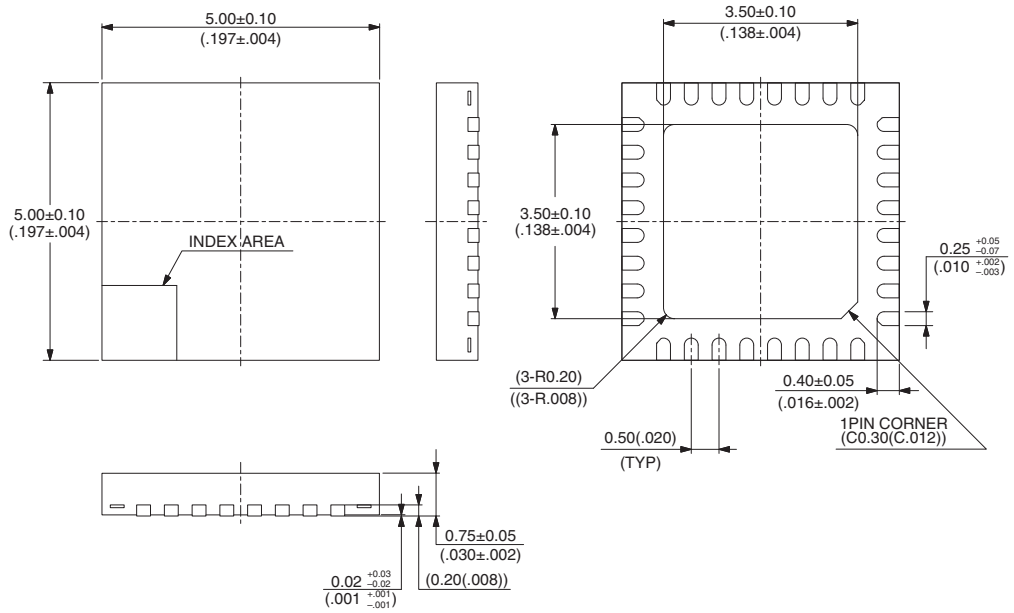
Dimensions in mm (inches).
Note: The values in parentheses are reference values

(Continued)

(Continued)

32-pin plastic QFN		
	Lead pitch	0.50 mm
	Package width × package length	5.00 mm × 5.00 mm
	Sealing method	Plastic mold
	Mounting height	0.80 mm MAX
	Weight	0.06 g
(LCC-32P-M19)		

32-pin plastic QFN
(LCC-32P-M19)



Dimensions in mm (inches).
Note: The values in parentheses are reference values.

Document History

Document Title: MB95F332H/F332K/F333H/F333K/F334H/F334K F^{2}MC-8FX MB95330H Series 8-bit Microcontrollers Document Number: 002-07522				
Revision	**ECN**	**Orig. of Change**	**Submission Date**	**Description of Change**
**	—	AKIH	04/12/2010	Migrated to Cypress and assigned document number 002-07522. No change to document contents or format.
*A	5181238	AKIH	04/04/2016	Updated to Cypress template